

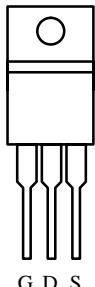
P-Channel Enhancement-Mode Transistor

Product Summary

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
-60	0.045	-40

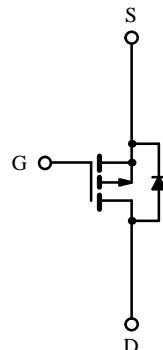
175°C Rated
Maximum Junction Temperature

TO-220AB



DRAIN connected to TAB

Top View



P-Channel MOSFET

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	-40	A
		-30	
Pulsed Drain Current	I_{DM}	-100	A
Avalanche Current	I_{AR}	-40	
Avalanche Energy	E_{AS}	90	mJ
Repetitive Avalanche Energy ^a	E_{AR}	45	
Power Dissipation	P_D	125	W
		62	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 175	°C

Thermal Resistance Ratings

Parameter	Symbol	Typical	Maximum	Unit
Junction-to-Ambient	R_{thJA}	80	1.2	°C/W
Junction-to-Case	R_{thJC}			
Case-to-Sink	R_{thCS}	1.0		

Notes:

a. Duty cycle $\leq 1\%$.

Subsequent updates to this data sheet may be obtained via facsimile by calling Siliconix FaxBack, 1-408-970-5600. Please request FaxBack document #1433.

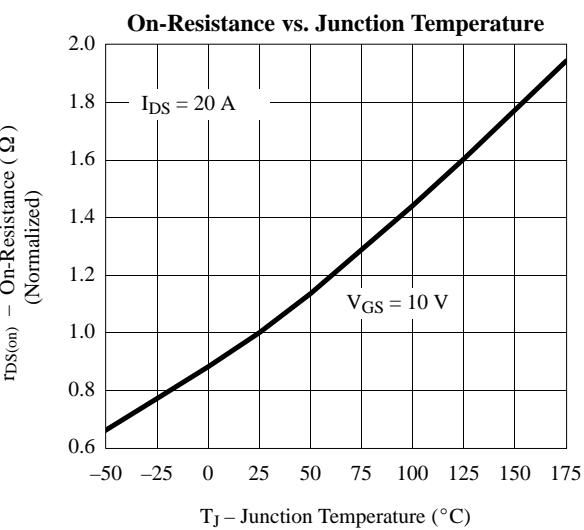
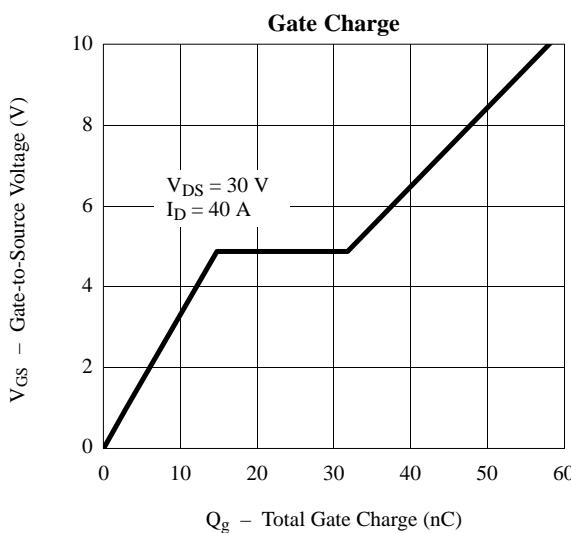
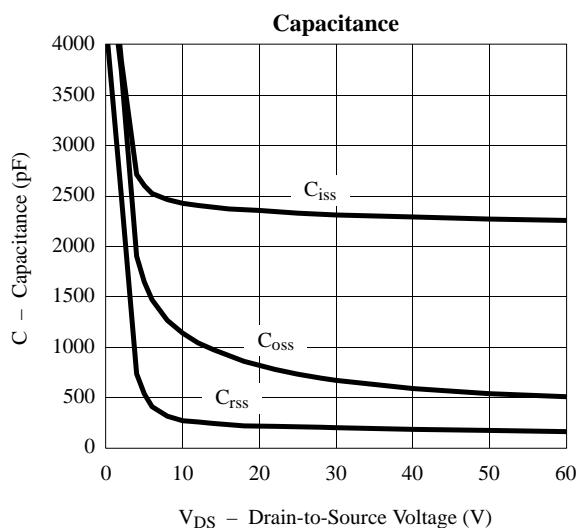
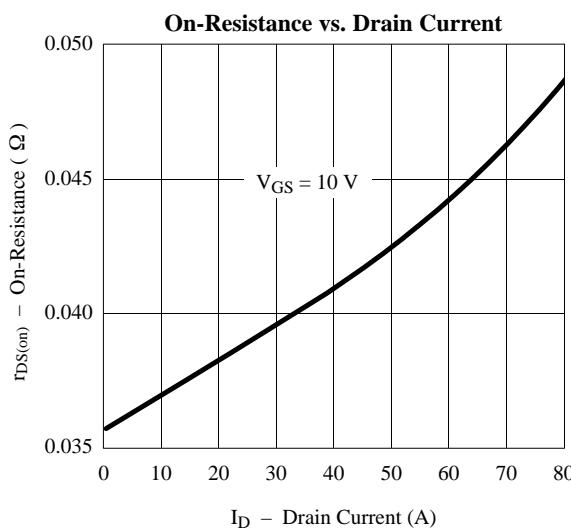
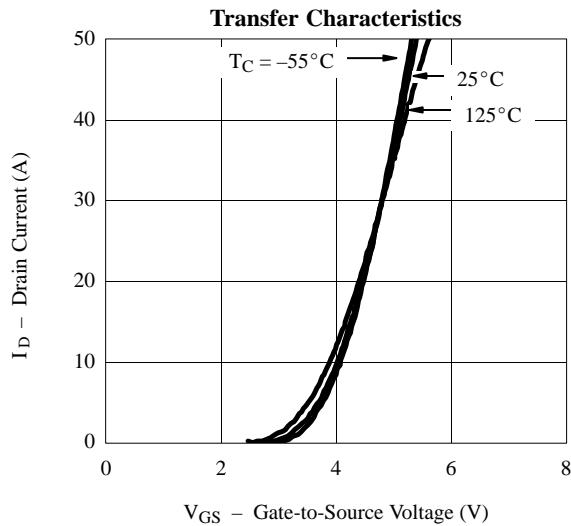
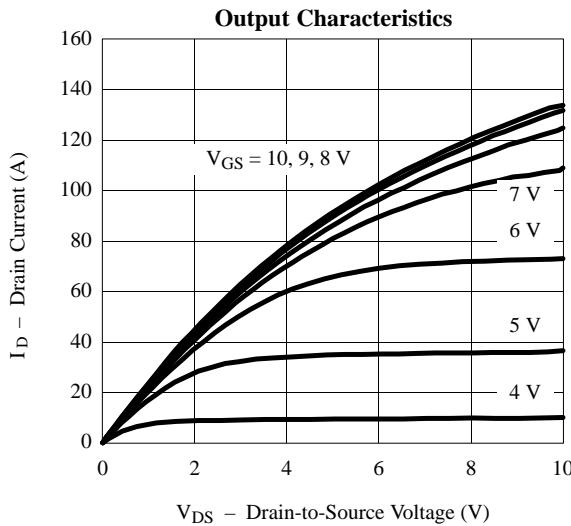
Specifications ($T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typ ^a	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-60			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -1 \text{ mA}$	-1		-3	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}, V_{\text{GS}} = \pm 20 \text{ V}$			± 500	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -48 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			-25	
		$V_{\text{DS}} = -48 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 125^\circ\text{C}$			-250	μA
		$V_{\text{DS}} = -48 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 175^\circ\text{C}$			-500	
On-State Drain Current ^b	$I_{\text{D}(\text{on})}$	$V_{\text{DS}} = -10 \text{ V}, V_{\text{GS}} = -10 \text{ V}$	-40			A
Drain-Source On-State Resistance ^b	$r_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10 \text{ V}, I_D = -20 \text{ A}$		0.038	0.045	
		$V_{\text{GS}} = -10 \text{ V}, I_D = -20 \text{ A}, T_J = 125^\circ\text{C}$			0.080	Ω
		$V_{\text{GS}} = -10 \text{ V}, I_D = -20 \text{ A}, T_J = 175^\circ\text{C}$			0.090	
Forward Transconductance ^b	g_{fs}	$V_{\text{DS}} = -15 \text{ V}, I_D = -20 \text{ A}$		28		S
Dynamic^a						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = -25 \text{ V}, f = 1 \text{ MHz}$		2600		
Output Capacitance	C_{oss}			800		pF
Reverse Transfer Capacitance	C_{rss}			200		
Total Gate Charge ^c	Q_g	$V_{\text{DS}} = -30 \text{ V}, V_{\text{GS}} = -10 \text{ V}, I_D = -40 \text{ A}$		60	100	
Gate-Source Charge ^c	Q_{gs}			15	20	nC
Gate-Drain Charge ^c	Q_{gd}			17	50	
Turn-On Delay Time ^c	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -30 \text{ V}, R_L = 1.5 \Omega$ $I_D \cong -20 \text{ A}, V_{\text{GEN}} = -10 \text{ V}, R_G = 2.5 \Omega$		11	30	
Rise Time ^c	t_r			12	35	ns
Turn-Off Delay Time ^c	$t_{\text{d}(\text{off})}$			70	140	
Fall Time ^c	t_f			75	150	
Source-Drain Diode Ratings and Characteristics ($T_C = 25^\circ\text{C}$)						
Continuous Current	I_S	$I_F = -40 \text{ A}, V_{\text{GS}} = 0 \text{ V}$			-40	
Pulsed Current	I_{SM}				-100	A
Forward Voltage ^b	V_{SD}			-1.2	-1.6	V
Reverse Recovery Time	t_{rr}	$I_F = -40 \text{ A}, dI_F/dt = 100 \text{ A}/\mu\text{s}$		81		ns
Peak Reverse Recovery Current	$I_{\text{RM}(\text{REC})}$			7		A
Reverse Recovery Charge	Q_{rr}			0.3		μC

Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- c. Independent of operating temperature.

Typical Characteristics (25°C Unless Otherwise Noted)



Typical Characteristics (25°C Unless Otherwise Noted)

